

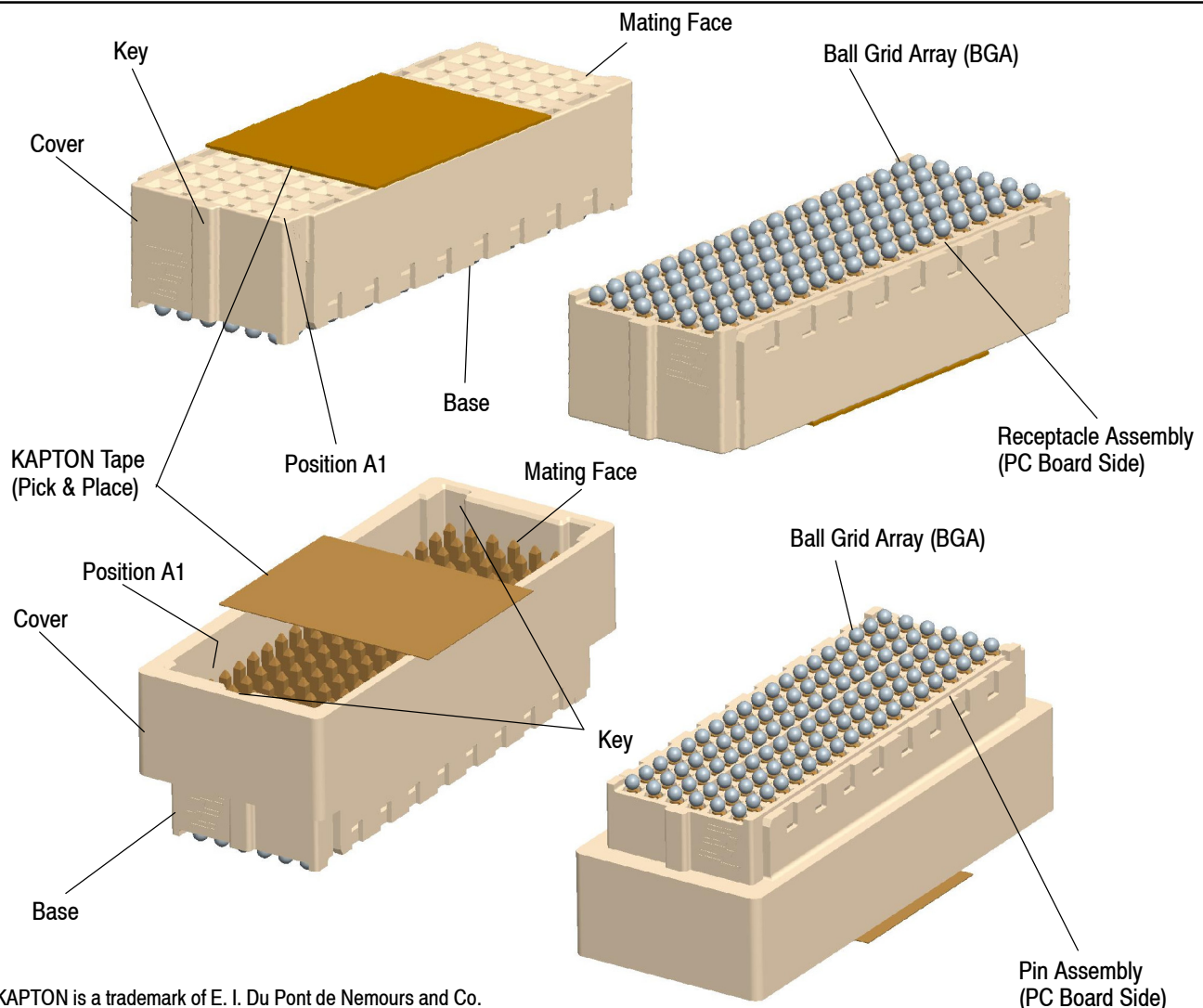
NOTE



All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters. Unless otherwise specified, dimensions have a tolerance of ± 0.13 and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION (Figure 1)


This specification covers the application of Mezalok Stacking Connectors used to meet or exceed the requirements of XMC2.0 per the VITA 61 standard. The VITA 61 standard defines performance requirements for a rugged, high-speed stacking connector system. These requirements include mating durability of 500 cycles minimum and signal transmission speeds of 5+GHz. The connectors are available in a plug assembly and receptacle assembly that provide a connection between two parallel printed circuit (pc) boards. the connectors are available in 60 and 114 positions (size - see Figure 2). The plug is a constant nominal height of 4 mm, and the receptacles are available with nominal heights of 6, 8, and 14 mm.



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Figure 1

NOTE



Not all connectors are tooled. Call Product Information at the number at the bottom of this page for availability.

Each connector consists of a cover and base (except the receptacle assembly with a nominal height of 14 mm which includes a spacer). The cover is on the mating face of the connector and contains contacts; and the base is on the pc board side of the connector and contains solder balls. The connectors use a Ball Grid Array (BGA) for solder attachment to the pc board.

The connectors are supplied in anti-static pocket tape packaging. KAPTON tape is attached to the connector for pickup and placement by automated equipment with vacuum pick-up; however, the tape is not used for placement by hand or when using mechanical grippers that grip the outside of the connector.

Position A1 is laser-marked on the connector covers. To assure proper mating orientation, the connectors are keyed at both ends. For initial alignment during mating, the chamfered lead-in around the perimeter of the pin assembly captures and guides the cover of the receptacle assembly. This lead-in also allows for blind mating.

When corresponding with TE Connectivity Personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.

1.1. Specifics

CONNECTOR SPECIFIC	CONNECTOR SIZE	
	60	114
Connector Length	15.67	27.10
Connector Width	11.0	11.0

Figure 2

1.2. Electrical Performance

These connectors are designed with close edge coupling to dedicated ground contacts on each side of the signal contacts, matching the impedance between contact pairs. Typical electrical performance is given in Figure 3.

TEST	1:1 DIFFERENTIAL PAIR	1:1 SINGLE-ENDED CONNECTION
Impedance at 50 ps (10% to 90%)	85-110 Ohms	50-60 Ohms
Bandwidth (3 dB)	5+ GHz	5 GHz
Multi-Active NEXT at 50 ps (10% to 90%)	< 2%	< 2%

Figure 3

2. REFERENCE MATERIAL

2.1. Revision Summary

- Initial release of document

2.2. Customer Assistance

Reference Product Base Part Numbers 2102060, 2102061 and Product Code L724 are representative of Mezalok Stacking Connectors. Use of these numbers will identify the product line and expedite your inquiries through a service network established to help you obtain product and tooling information. Such information can be obtained through a local TE Representative or, after purchase, by calling Product Information at the number at the bottom of page 1.

2.3. Drawings

Customer Drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the Customer Drawings and this specification or with any other technical documentation supplied, the Customer Drawing takes precedence.

2.4. Specifications

Product Specification 108-2411 provides product performance and test information.

3. REQUIREMENTS

3.1. Safety

Do not stack product shipping containers so high that the containers buckle or deform.

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3.2. PC Board

NOTE The design of the pc board affects connector reliability and performance.



A. Solder Pads

The pc board solder pads must be solderable in accordance with Electronic Industries Alliance (EIA) 364-52. The pad diameter shall be 0.64 ± 0.05 mm with a true position of diameter of 0.10 mm Regardless of Feature Size (RFS). The pad shall be copper defined with Organic Solderability Preservative (OSP) or Hot Air Solder Leveling (HASL).

B. Layout

Per VITA 42 XMC mezzanine card and carrier board footprints. See Figure 4.

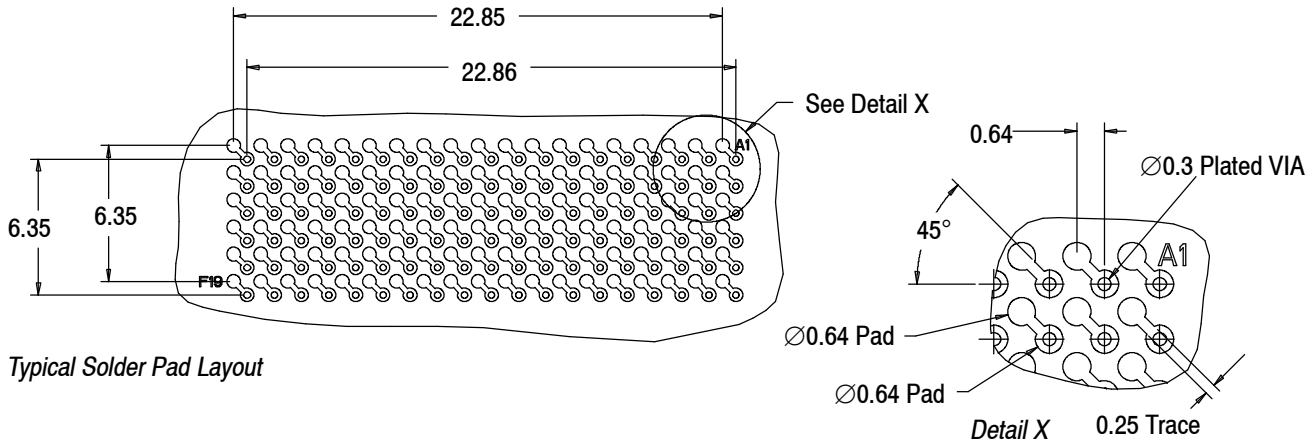


Figure 4

3.3. Tape Packaging

Per EIA-481-D. See Figure 5.

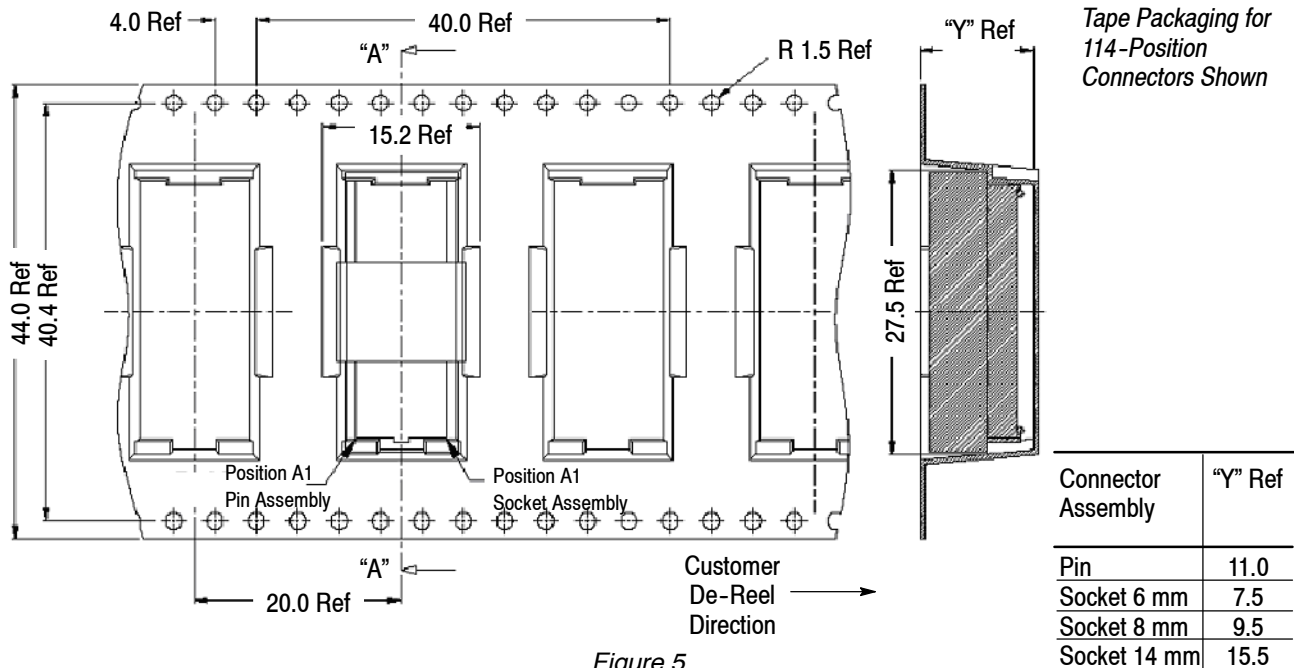


Figure 5

3.4. Solder Process

A. Solder Paste

A no-clean solder paste is recommended.

B. Solder Volume

Solder volume must be approximately 0.049 mm³ per pad.

C. Solder Mask

The solder mask opening diameter must be greater than the pc board pad diameter and is recommended to be $\varnothing 0.89$ mm nomially. The pc board vias should not be directly under the solder pads of the ball grid array. The component side of the pc board shall be fully covered with solder mask. The mask may be truncated along the interconnect trace.

D. Stencil

A stencil thickness of 0.157 mm is recommended. A round aperture diameter of 0.64 mm is recommended.

E. Reflow

1. To obtain temperature equalization at all ball grid array locations, the assembly should be soaked at a temperature above 145°C [293°F] between 60 and 80 seconds prior to reflow.
2. The reflow time at temperatures above 183°C [361°F] for *tin-lead* solder application and above 218°C [424°F] for *lead-free* solder application should be from 60 to 90 seconds for the perimeter of the solder ball grid array and at least 30 seconds for the center of the solder ball grid array.
3. Peak temperature should be between 210°C and 220°C [410°F and 428°F] for *tin-lead* solder application and between 230°C and 240°C [446°F and 464°F] for *lead-free* solder application for no more than 10 seconds.
4. The total cumulative time to ramp up, soak, and reflow shall be limited to 280 seconds.
5. A nitrogen environment of 4,000 ppm O₂ or lower can improve solderability; however, is not required.
6. The ramp rate should be less than 2.0°C [35.6°F] per second.

NOTE

Recommended temperatures are for the top surface of the pc board within or near the connector solder ball grid array.



F. Solder Profile

A sample solder profile is shown in Figure 6.

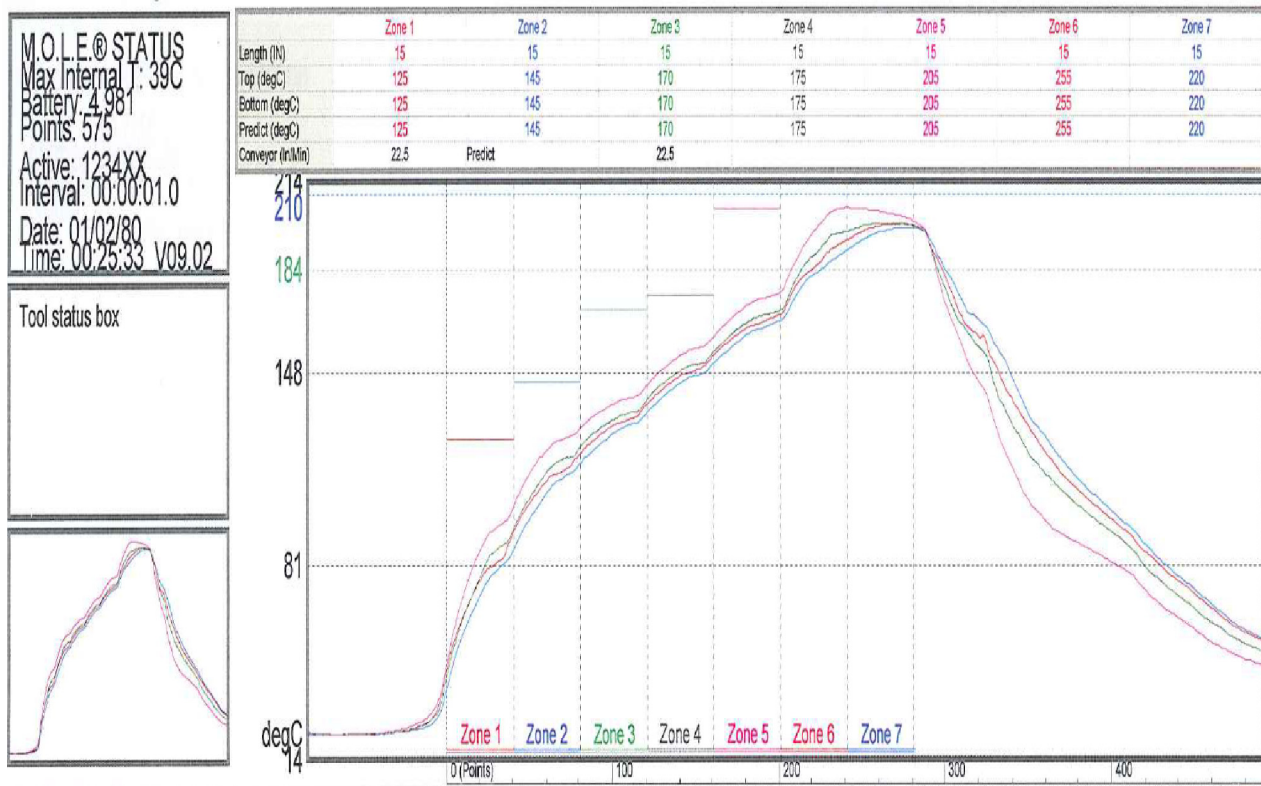


Figure 6

G. Cleaning

After reflow, the assembly can be washed with an appropriate cleaner to remove any residue or contaminants.

3.5. Assembly Inspection

The connectors must be inspected visually for damage and cleanliness. Visual inspection of the solder joint of the ball grid array is not feasible. Solder joints can be inspected using X-ray techniques. A solder pad that is shaped different than the solder ball might assist in viewing the solder plane. Electrical testing may be performed; however, caution must be taken to avoid damage to the connector contacts during the electrical testing.

3.6. Mating and Unmating

A. Mating

The KAPTON tape must be removed from both connectors before mating.

These connectors should be mated straight.

Align the connectors and when the keys start to enter the keyways, push at the approximate center of the connector into the mating connector until the face of the receptacle cover bottoms on the face of the plug.

Because of the asymmetric keying, reverse mating is impossible (the key end of the receptacle cannot be inserted into the non-keyway end of the plug). Both connectors have a lead-in around the perimeter that will allow blind mating.

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B. Unmating

These connectors can be unmated by pulling them straight apart or by “rocking” the connectors from side-to-side while pulling them apart. Refer to Figure 7.

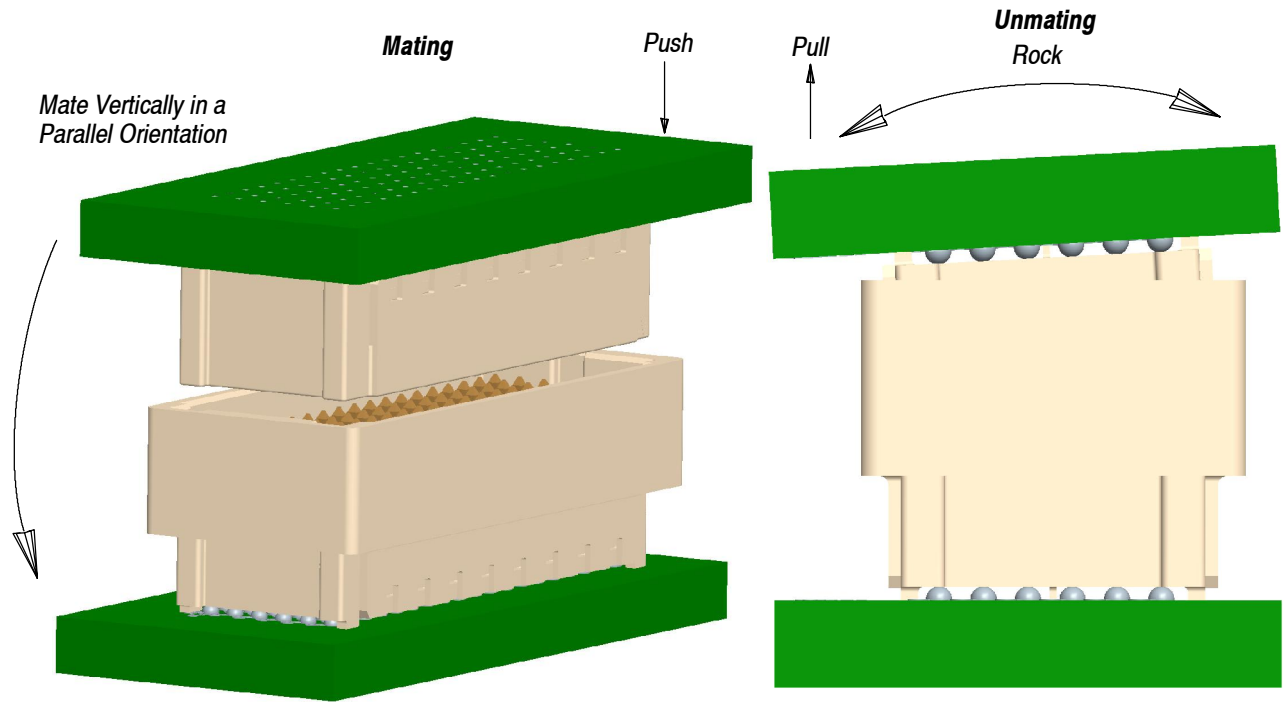
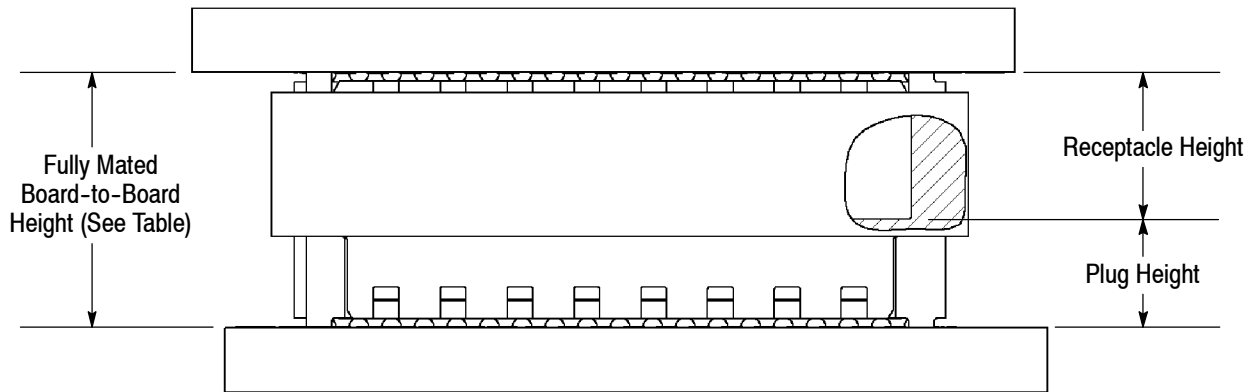


Figure 7

3.7. Fully Mated Connector Board-to-Board Height

The mated connector board-to-board height is affected by the pc board pad size, pad plating, solder paste, and solder profile. The fully mated connector board-to-board height is given in Figure 8.



PLUG HEIGHT (mm)	RECEPTACLE HEIGHT (mm)	FULLY MATED BOARD-TO-BOARD STACK HEIGHT (mm)
4.0	6.0	10.0
	8.0	12.0
	14.0	18.0

Figure 8

4. QUALIFICATION

Mezalok Stacking Connectors are qualified to Product Specification 108-2411 per Test Report 501-736.

5. TOOLING

The connectors can be placed on the pc board manually; however, it is recommended that the connectors be placed on the pc board using automated equipment. Fixturing may be used to assure true position accuracy to properly locate the connectors—the fixturing must reference the datum surfaces detailed on the customer drawing to ensure reliable placement.

6. VISUAL AID

Figure 9 shows a typical application of Mezalok Stacking Connectors. This illustration should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.

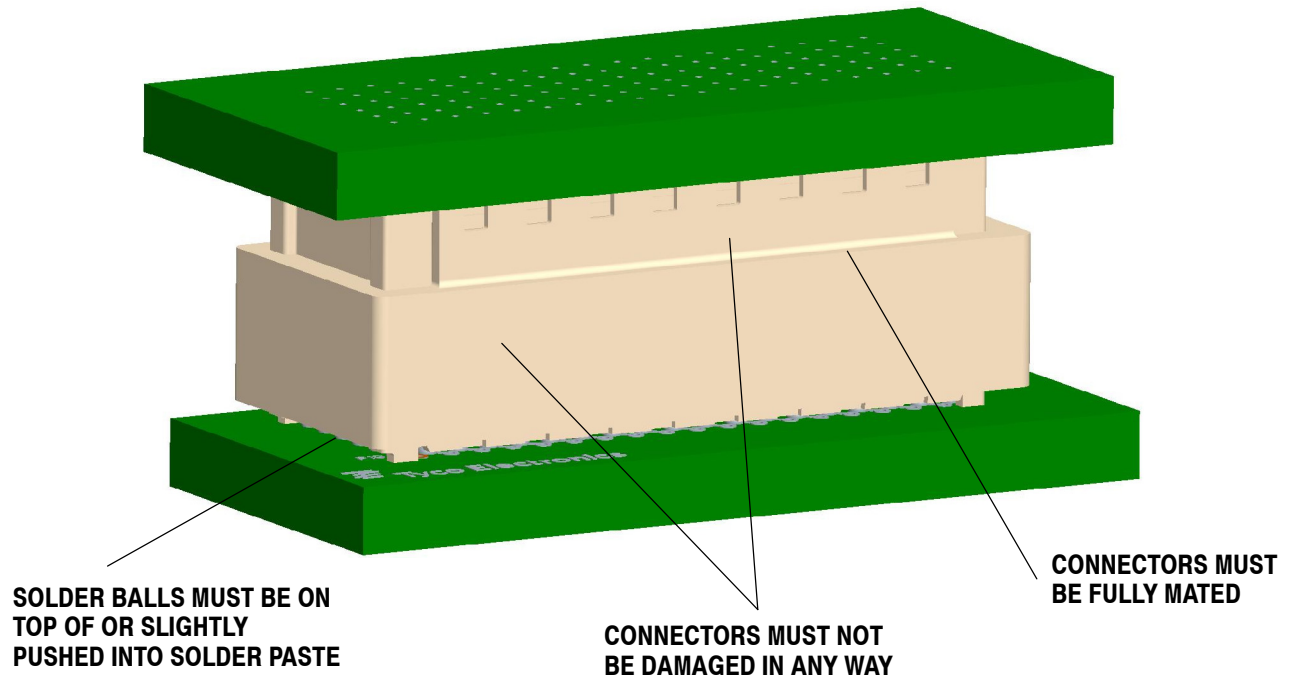


FIGURE 9. VISUAL AID